

GAU 2878
#2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Thomas P. Glenn, Steven Webster, Markus K. Liebhard
Assignee: Amkor Technology, Inc.
Title: CHIP SIZE IMAGE SENSOR WIREBOND PACKAGE FABRICATION METHOD
Serial No.: 09/712,314 Filed: November 13, 2000
Examiner: Unknown Group Art 2878
Unit:
Docket No.: G0026M

Monterey, CA
February 13, 2001

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT
UNDER §1.97 (b)

Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicant(s) wish to call the following documents (a copy of each is enclosed) to the attention of the Examiner.

U.S. PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	NAME
1)	5,867,368	2/2/99	Glenn
2)	5,821,532	10/13/98	Beaman et al.

A PTO form 1449 listing these documents is enclosed.

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This application is related to: Webster et al., U.S. Patent Application Serial No. 09/490,717, entitled "PROTECTED IMAGE SENSOR PACKAGE", filed January 25, 2000; Webster et al., U.S. Patent Application Serial No. 09/491,112, entitled "PROTECTED IMAGE SENSOR PACKAGE FABRICATION METHOD", filed January 25, 2000; Glenn et al., U.S. Patent Application Serial No. 09/610,314, entitled "WAFER SCALE IMAGE SENSOR PACKAGE", filed July 5, 2000; Glenn et al., U.S. Patent Application Serial No. 09/610,309, entitled "WAFER SCALE IMAGE SENSOR PACKAGE FABRICATION METHOD", filed July 5, 2000; Glenn et al., U.S. Patent Application Serial No. 09/577,692, entitled "IMAGE SENSOR PACKAGE HAVING SEALED CAVITY OVER ACTIVE AREA", filed May 22, 2000; Glenn et al., U.S. Patent Application Serial No. 09/576,595 entitled "METHOD OF FORMING AN IMAGE SENSOR PACKAGE HAVING SEALED CAVITY OVER ACTIVE AREA", filed May 22, 2000; Glenn et al., U.S. Patent Application Serial No. 09/711,993, entitled "CHIP SIZE IMAGE SENSOR WIREBOND PACKAGE", filed November 13, 2000; Glenn et al., U.S. Patent Application Serial No. 09/712,313, entitled "CHIP SIZE IMAGE SENSOR BUMPED PACKAGE", filed November 13, 2000; and Glenn et al., U.S. Patent Application Serial No. 09/711,994, entitled "CHIP SIZE IMAGE SENSOR BUMPED PACKAGE FABRICATION METHOD", filed November 13, 2000.

Citation of the above documents shall not be construed as:

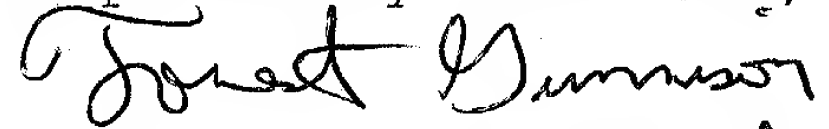
1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, other than as described above; or

3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage for First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on February 13, 2001.


Attorney for Applicant(s) February 13, 2001
Date of Signature

Respectfully submitted,


Reg No 32,889 for
Serge J. Hodgson
Attorney for Applicant(s)
Reg. No. 40,017
(831) 655-0880